

AP12N65D

N-Channel Enhancement Mosfet

AIPOWER

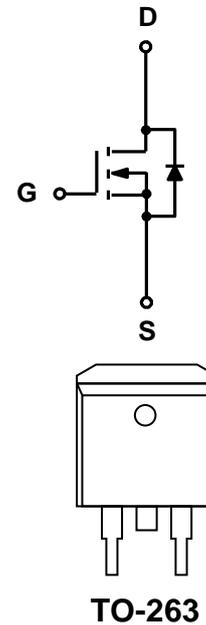
DATA SHEET

Features

- 650V,12A
 $R_{DS(ON)} < 800m\Omega @ V_{GS}=10V$ TYP:605m Ω
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- LED lighting power



Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity (PCS) |
|----------------|----------|----------------|-----------|------------|----------------|
| 12N65D | AP12N65D | TO-263 | - | - | 800 |

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|-----------------|-----------|---------------------------|
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ± 30 | V |
| Continuous Drain Current ($T_a=25^\circ\text{C}$) | I_D | 12 | A |
| Avalanche Current ⁽¹⁾ | I_{AS} | 48 | A |
| Pulsed Drain Current ⁽¹⁾ | I_{DM} | 48 | A |
| Single Pulsed Avalanche Energy ⁽²⁾ | E_{AS} | 311 | mJ |
| Power Dissipation | P_D | 225 | W |
| Thermal Resistance from Junction to Case | $R_{\theta JC}$ | 0.56 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance from Junction to Ambient | $R_{\theta JA}$ | 62.5 | $^\circ\text{C}/\text{W}$ |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -55~ +150 | $^\circ\text{C}$ |

MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|---------------|---|-----|-------|-----------|-----------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 650 | - | - | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 650V, V_{GS} = 0V, T_J = 25^\circ\text{C}$ | - | - | 1 | μA |
| Gate-body leakage current | I_{GSS} | $V_{GS} = \pm 30V, V_{DS} = 0V$ | - | - | ± 100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2.0 | 3.0 | 4.0 | V |
| Drain-source on-resistance ⁽³⁾ | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 3.0A$ | - | 573 | 790 | $m\Omega$ |
| | | $V_{GS} = 10V, I_D = 6.0A$ | | 605 | 800 | $m\Omega$ |
| Dynamic characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$ | - | 2100 | - | pF |
| Output Capacitance | C_{oss} | | - | 162.6 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 7.0 | - | |
| Switching characteristics | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 325V, I_D = 12A, R_G = 25\Omega$ | - | 27.6 | - | ns |
| Turn-on rise time | t_r | | - | 52.6 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 75.2 | - | |
| Turn-off fall time | t_f | | - | 42.5 | - | |
| Total Gate Charge | Q_g | $V_{DS} = 520V, I_D = 12A,$ $V_{GS} = 10V$ | - | 37 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 7.4 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 18 | - | |
| Source-Drain Diode characteristics | | | | | | |
| Diode Forward voltage | V_{SD} | $T_J = 25^\circ\text{C}, V_{GS} = 0V, I_S = 12A$ | - | - | 1.4 | V |
| Diode Forward current | I_S | $T_C = 25^\circ\text{C}$ | - | - | 12 | A |
| Body Diode Reverse Recovery Time | t_{rr} | $T_J = 25^\circ\text{C}, I_F = 12A, di/dt = 100A/\mu s$ | | 566 | | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | $T_J = 25^\circ\text{C}, I_F = 12A, di/dt = 100A/\mu s$ | | 58 | | uc |

Notes:

1. Pulse width limited by maximum junction temperature
2. $L=20mH, V_{DD}=100V, V_G=10V, R_G=25\Omega$, starting $T_J=25^\circ\text{C}$
3. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

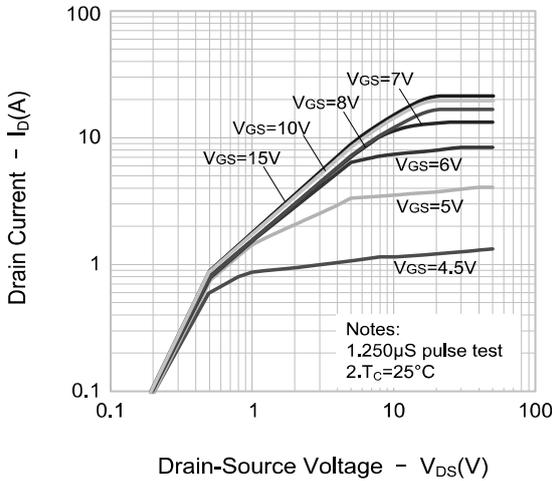


Figure 2. Transfer Characteristics

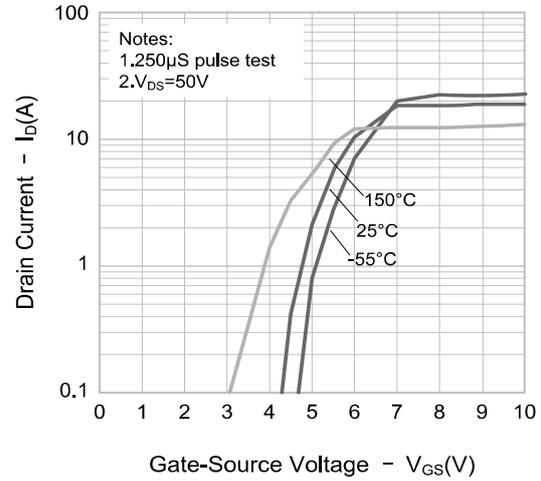


Figure 3. On-resistance vs. Drain Current

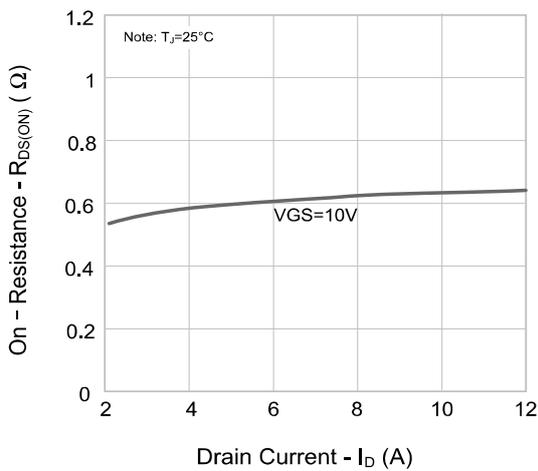


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

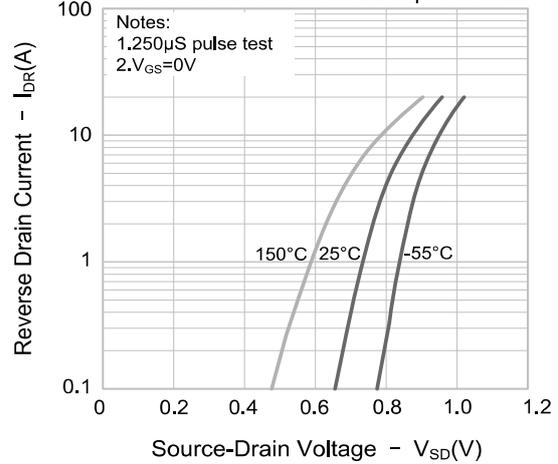


Figure 5. Capacitance Characteristics

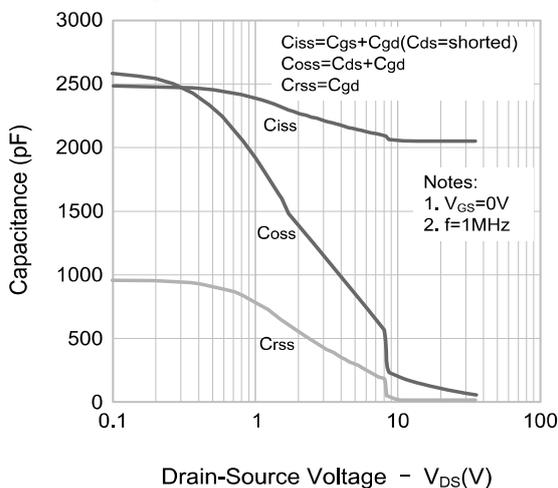
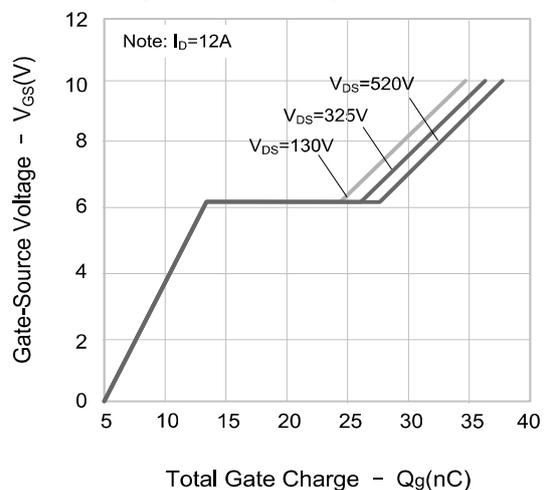


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics

Figure 7. Breakdown Voltage Variation vs. Temperature

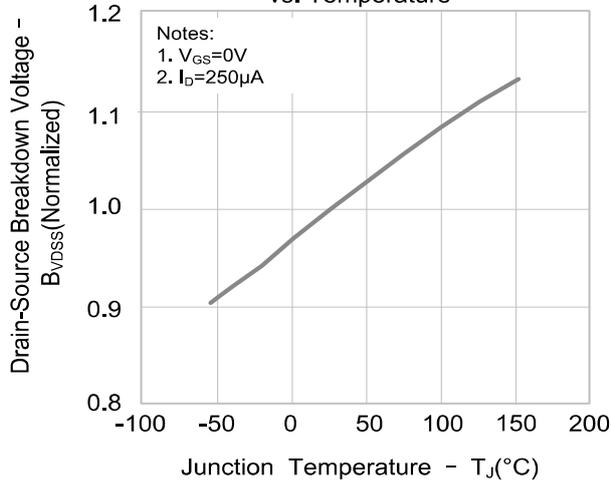


Figure 8. On-resistance vs. Temperature

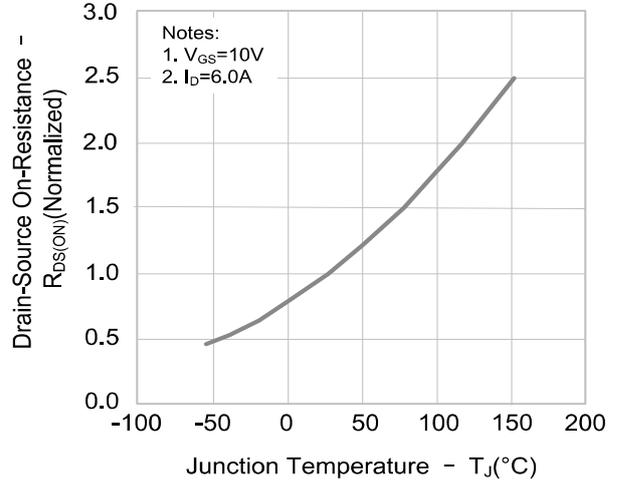
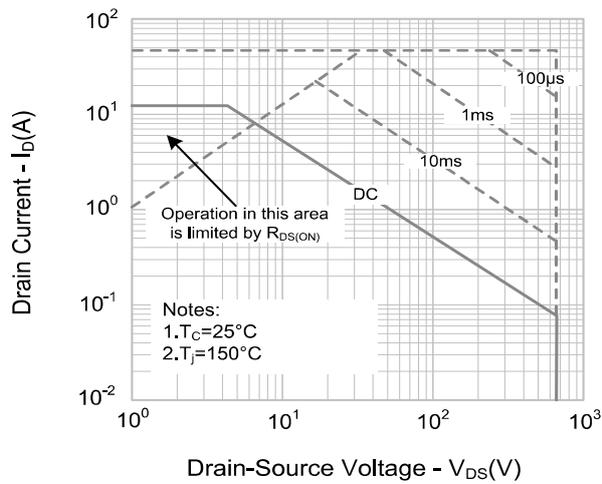
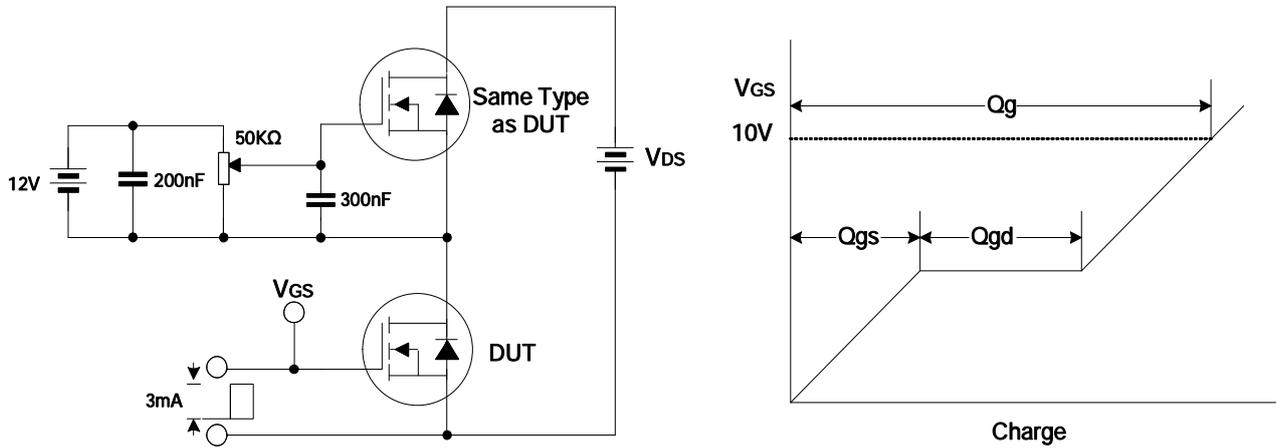


Figure 9. Max. Safe Operating Area

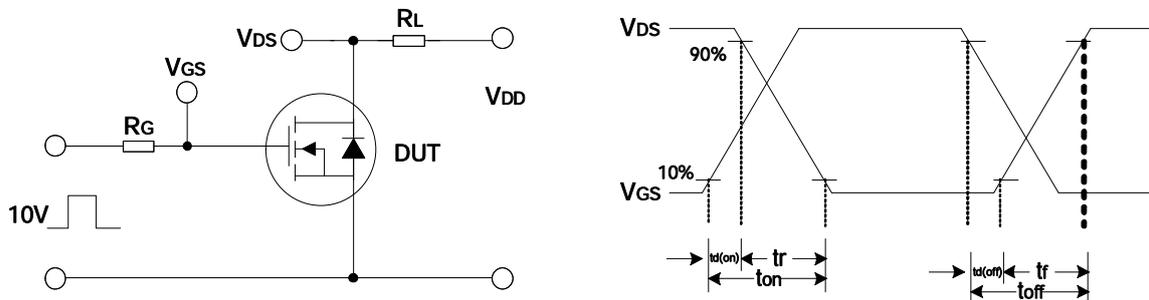


TYPICAL TEST CIRCUIT

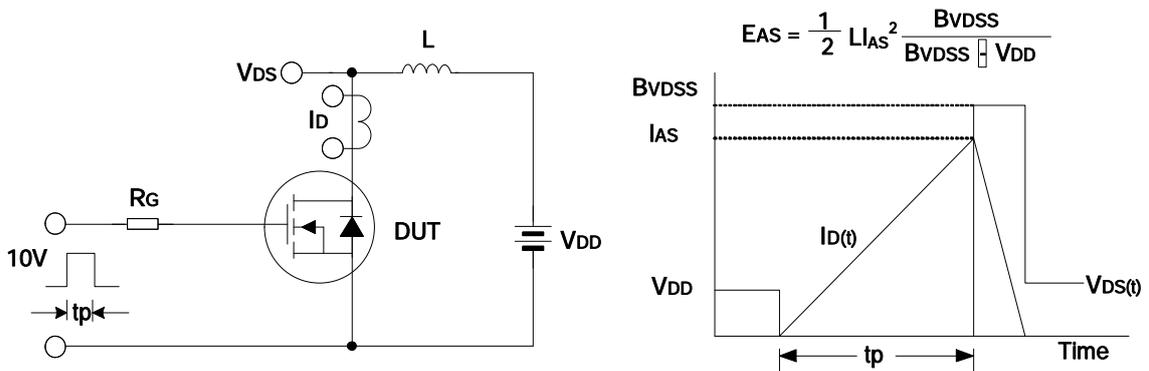
Gate Charge Test Circuit & Waveform



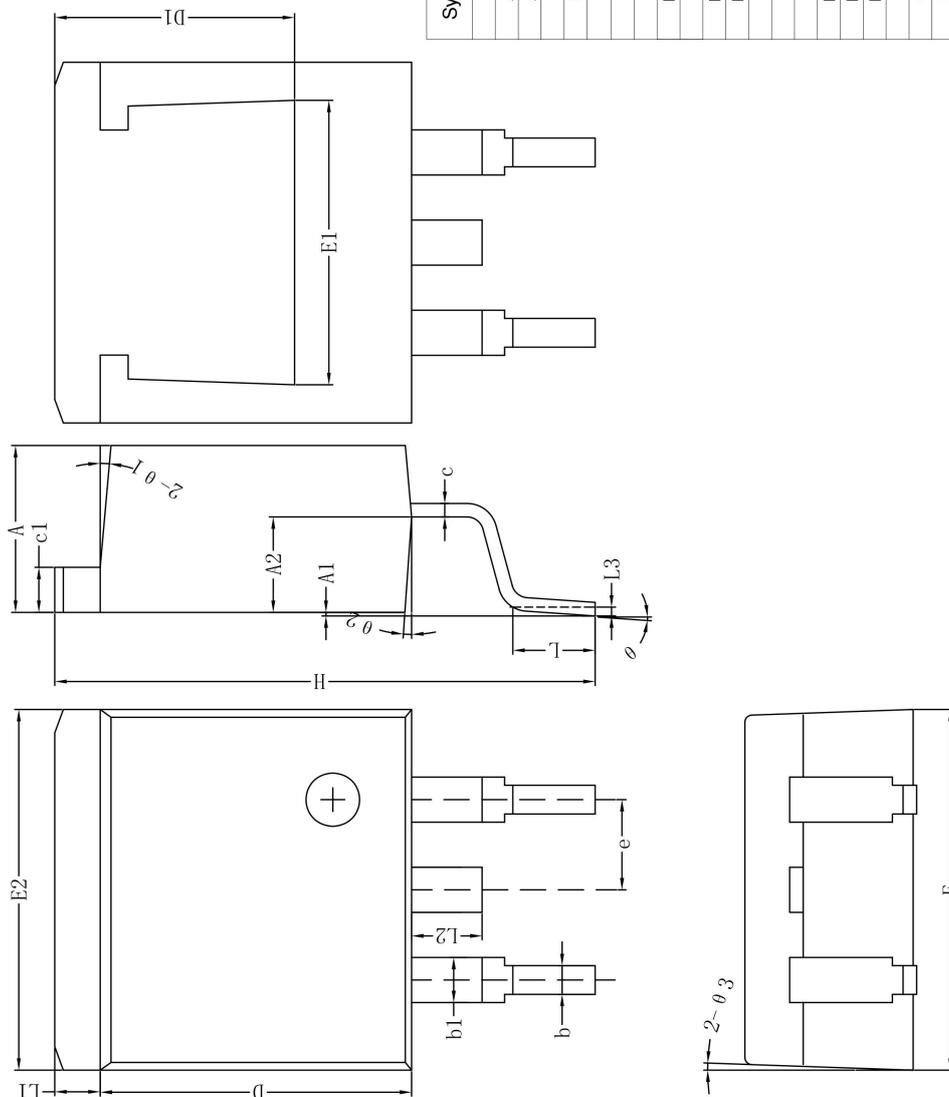
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



Package Dimensions of TO-263



| Symbol | Size /mm | | |
|--------|----------|---------|-------|
| | MIN | NOM | MAX |
| A | 4.55 | 4.70 | 4.85 |
| A1 | 0 | 0.10 | 0.25 |
| A2 | 2.59 | 2.69 | 2.89 |
| b | 0.71 | 0.81 | 0.96 |
| b1 | | 1.27 | |
| c | 0.36 | 0.38 | 0.61 |
| c1 | 1.17 | 1.27 | 1.37 |
| D | 8.55 | 8.70 | 8.85 |
| D1 | 6.70 | | 7.70 |
| E | 10.01 | 10.16 | 10.31 |
| E1 | 7.2 | | 8.1 |
| E2 | 9.98 | 10.08 | 10.18 |
| e | | 2.54 | |
| H | 14.7 | 15.1 | 15.5 |
| L | 2.00 | 2.30 | 2.70 |
| L1 | 1.17 | 1.27 | 1.40 |
| L2 | | | 2.20 |
| L3 | | 0.25BSC | |
| theta | 0 | - | 8° |
| theta | 0 | | 5° |
| theta | 0 | | 4° |
| theta | 0 | | 4° |